

OL-NX1A4WP

wafer level chip-scale package; 42 bumps; 3.56 x 3.41 x 0.57 mm (backside coating included)

8 February 2016

Package information

1. Package summary

Terminal position code	B (bottom)
Package type descriptive code	WLCSP
Package type industry code	WLCSP42
Package style descriptive code	UC (uncased chip)
Package style suffix code	NA (not applicable)
Package body material type	P (plastic)
Mounting method type	S (surface mount)
Issue date	19-1-2015

Table 1. Package summary

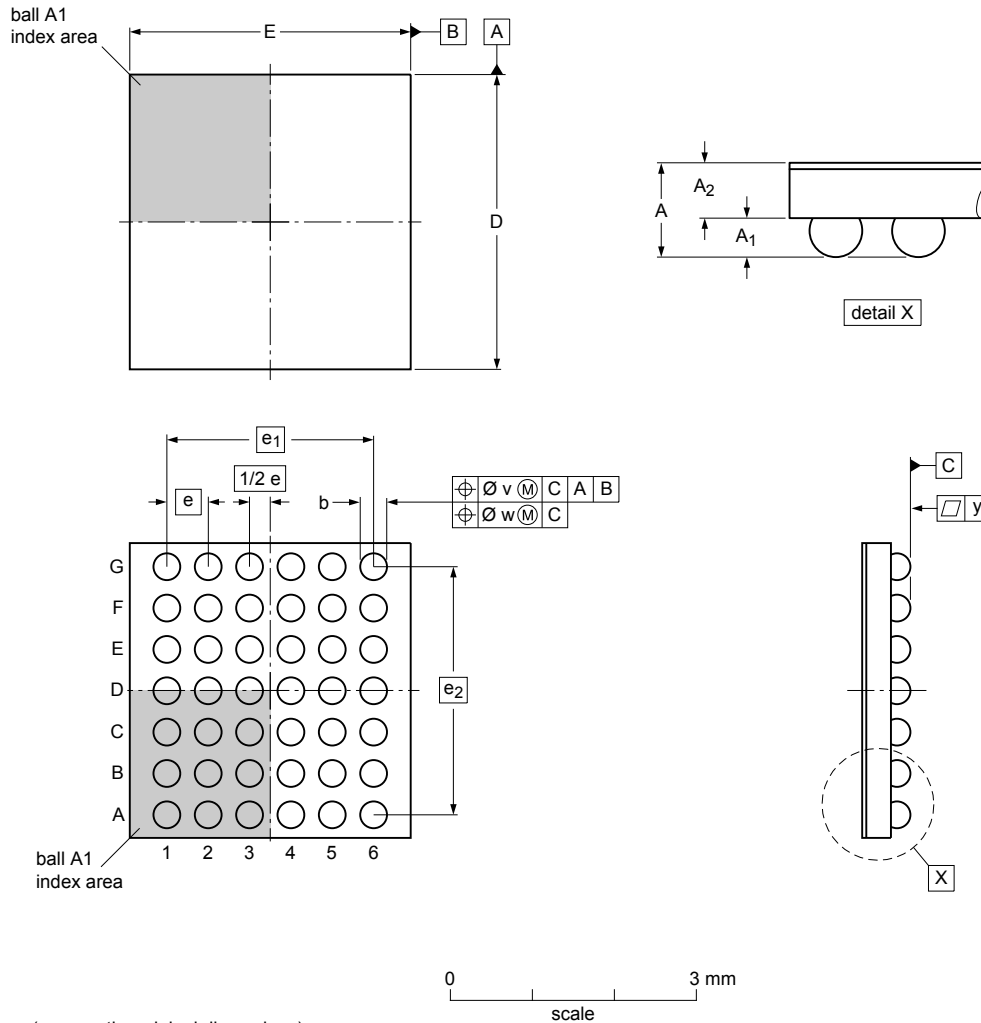
Symbol	Parameter	Min	Typ	Nom	Max	Unit
D	package length	3.54	-	3.56	3.58	mm
E	package width	3.39	-	3.41	3.43	mm
A	seated height	0.53	-	0.57	0.61	mm
e	nominal pitch	-	-	0.5	-	mm
n ₂	actual quantity of termination	-	-	42	-	



wafer level chip-scale package; 42 bumps; 3.56 x 3.41 x 0.57 mm (backside coating included)

2. Package outline

WLCSP42: wafer level chip-scale package; 42 bumps; 3.56 x 3.41 x 0.57 mm (backside coating included) NX1A4WP



Dimensions (mm are the original dimensions)

Unit	A	A ₁	A ₂	b	D	E	e	e ₁	e ₂	v	w	y
max	0.61	0.26	0.37	0.34	3.58	3.43						
nom	0.57	0.23	0.34	0.32	3.56	3.41	0.5	2.5	3.0	0.15	0.05	0.03
min	0.53	0.20	0.31	0.30	3.54	3.39						

Note:

1. Row material of solder ball 0.3 ± 0.03 mm
2. Backside coating 40 µm

wlcs42-nx1a4wp_po

Outline version	References			European projection	Issue date
	IEC	JEDEC	JEITA		
NX1A4WP					-15-01-15- 15-01-19

Fig. 1. Package outline WLCSP42 (OL-NX1A4WP)

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3.41 x 0.57 mm (backside coating included)

3. Legal information

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